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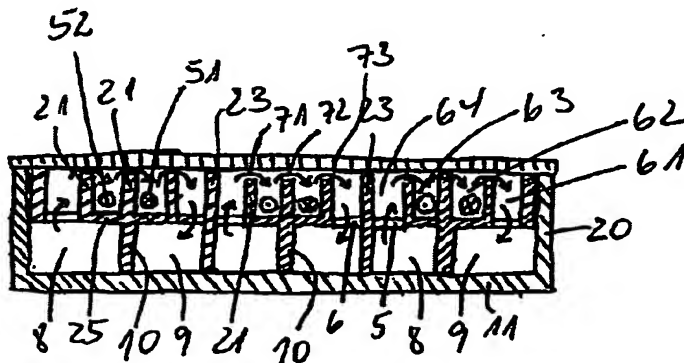
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(54) Title: FLOW DISTRIBUTING UNIT AND COOLING UNIT HAVING BYPASS FLOW



(57) Abstract: A cooling unit for cooling in
particular power semiconductors contains a
distributor for guiding liquid across a surface
to be cooled. The distributor comprises an
inlet manifold (8) and outlet manifold (9),
whereby the inlet and outlet manifolds are
connected through a flow cell, which has a
main flow channel (50). The main channel is
formed as a meandering sequence of channel
segments (61, 62, 63, 64). It has been found,
that the transfer of heat by the liquid in
the main flow channel can be improved by
introducing a bypass flow channel (71, 72,
73) which allows the flow of liquid from
the cell inlet to the cell outlet, wherein
the bypass flow channel interconnects the
channel segments of the main flow channel.